

## *FemtoLEED DLD L800 Configuration Guide and Specifications*



## **LEED** configuration

Base configuration				
Model	Order Code			
DLD L800		Femto-LEED optics for low energy electron beam application, with 3 grid high resolution retarding field analyzer, integral miniature electron gun, two 80 mm O.D. Long Life(TM) microchannel plates in chevron configuration with Au plating enhanced for pulsed mode, delay-line-anode, Mu-metal shield mounted on the CF8" (DN150CF) O.D. flange. Miniature Precision Electron Gun with beam current range 50 nA-1 fA with LaB6 single crystal filament. Port length: 300 mm standard or to be specify by user, additional parts changes as per user specification.		
LMX		Integral linear retraction based on 4 linear ball bearings up to 100 mm		
LPS075-D		Digital power supply (0-750 V) with USB interface and PC control software for Windows 10. True primary beam current and total emission measurements. Automatic start-up and shut down, 10 memory settings including standby and outgassing mode with timer, constant beam current mode controlled by filament current or Wehnelt voltage. All cables included.		
MCPS2		Electronics for two microchannel plates with digital displays of voltages and MCP load current measurements and protection.		
Options				
ISH		Integral shutter		
LaB <sub>6</sub>		LaB <sub>6</sub> single crystal filament instead of a tungsten wire filament		
DLA-TR8		Controller for delay line detector and computer interface PCI card		

## **LEED Software**

Software Options				
Model	Order			
	Code			
LIM-DLD		LEED pattern measurements, analysis software & hardware for Windows 10 including:		



- Automatic LEED pattern acquisition	
- Automatic I-V analysis with spot tracking	
- Automatic I-T analysis	
- Automatic spot profile analysis	

## **Detailed Specifications**

FemtoLEED DLD L800 optics				
Detector	Delay Line Detector with dynamic range 32 bit per channel, 75 microns spatial resolution and active area 145x145mm			
Angle of acceptance	77° from sample			
Retarding Field Analyzer	Concentric assembly of hemispherical grids			
Working distance from sample	15 mm			
Grid material	Gold coated tungsten wire mesh (100 mesh, 81% transparency)			
Energy resolution	0.2%			
Monitoring	8" standard viewport			
Linear motion	Up to 100 mm retraction from sample; linear ball bearing and acme thread with all spring electrical connections			
Integral shutter	Manual shutter driven by a rotary feedthrough			
Magnetic shielding	Mu metal cylinder with front cover for maximum attenuation			
Assembly	Extreme high vacuum compatibility with stainless steel, high alumina and Au-plated copper alloy materials			
Mounting	CF8" (DN150CF) double sided conflat flange with sample distance 145 mm – 400mm			
Bakeability	Under vacuum, 250°C maximum			
Integral miniature electro	on gun			
Beam energy	LEED: 0-750 eV			
Beam current	LEED: 2 $\mu$ A at 100 eV and 0.5 mm beam size			
Beam size	From 1 mm to 250 µm-adjusted by wehnelt potential, limited by			
	exchangeable aperture down to 50 µm			
Electron source	Tungsten 2% thoriated filament (standard) or single crystal LaB filament			
	(optional)			
Energy spread	0.45 eV (thoriated-tungsten filament)			
Overall size	10 mm lens diameter and 80 mm length			
Microchannel Plates				
Working area	75 mm			
L/D ratio	40:1			
Channel diameter	25 microns			
Center to center spacing	32 microns			
Plate thickness	1.0 mm			
Bias angle	8°			
Electron gain	10 <sup>7</sup> , operating in pulsed mode			
LPS075-D Electronics				
Beam Voltage	LPS075-D: negative 0-750 V			
Filament current	0-3.2 A Tungsten/ 0-2.1 A LaB₀			
Wehnelt voltage	0-37 V with respect to the filament			
Focus voltage	LEED: positive 70-180% of the beam voltage			
Retarding (grid) voltage	Negative 50-110% of the beam voltage			
Screen voltage	Positive 0-5000 V			
Emission current	1-200 μΑ			
Beam current	0.01-200 μΑ			
Monitoring	All voltages and currents			
Display	Vacuum fluorescent, displaying all voltages, currents and program functions			
On-board automation	5 pre-programmed and fully programmable operating programs for outgassing, stand-by, filament forming, beam voltage scanning, constant beam current and diagnostics			
Manual control	Of all voltages via rotary dials and selection switches			
PC control	PC software for full control of all functions via USB			



Protection	Over-voltage, over-current, and short circuit
Dimensions	3U 19" rack mount (5.25"/133 mm), depth of 17.5" (440 mm), weight 12 kg